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Electron contacts to crystalline silicon

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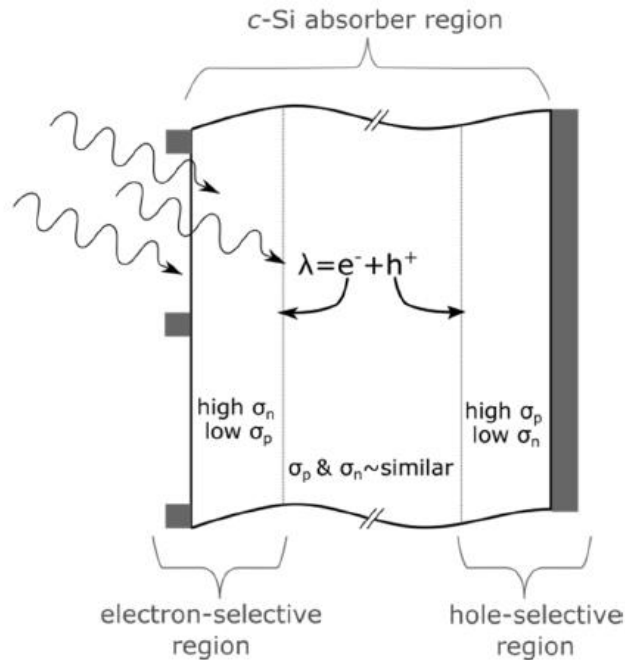
ÉCOLE POLYTECHNIQUE
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Berkeley
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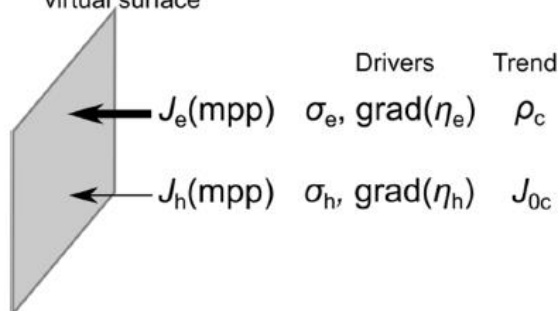


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What is a solar cell?



Electron-selective
virtual surface



majority carrier flow
causes a resistive loss



contact resistance ρ_c

minority carriers towards the
“wrong” contact region will
recombine



recombination current J_{0c}

$$J_{rec} = J_{0c} \exp\left(\frac{E_{Fn} - E_{Fp}}{kT}\right)$$

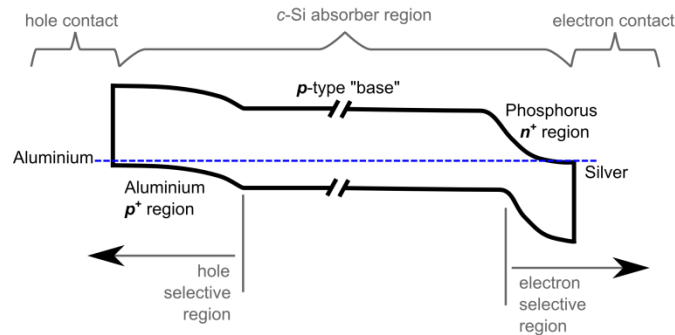
We need:

- **sufficient** conduction (low ρ_c)
- the **best** passivation possible (low J_{0c})

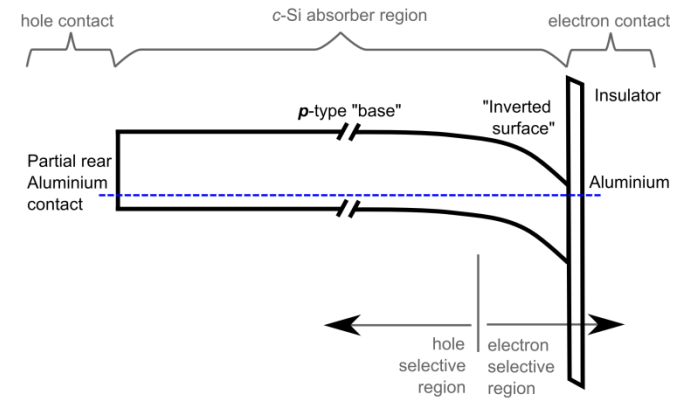
The c-Si family tree



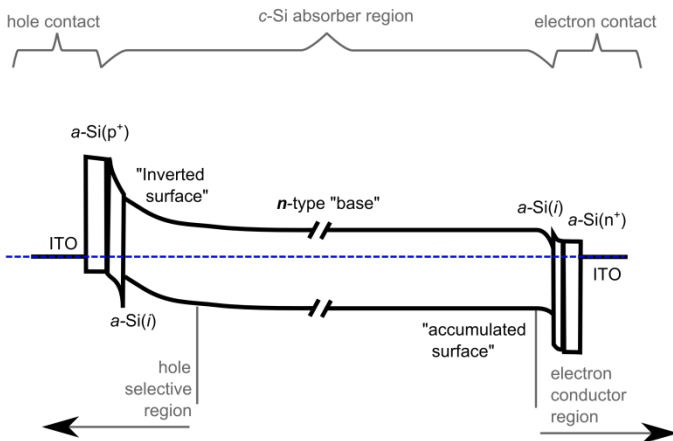
Homojunction solar cell



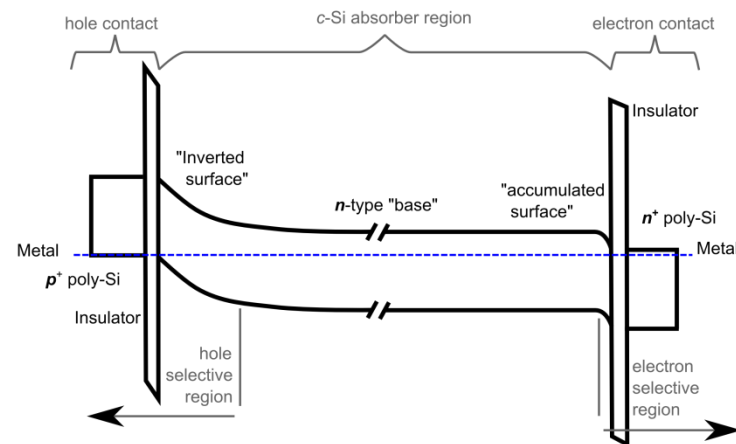
Inversion layer solar cell



Silicon heterojunction solar cell



Double polysilicon solar cell



Quantifying carrier selectivity



Contact resistivity ρ_c

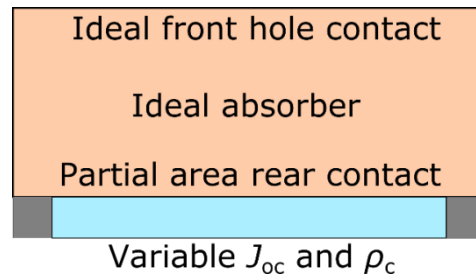
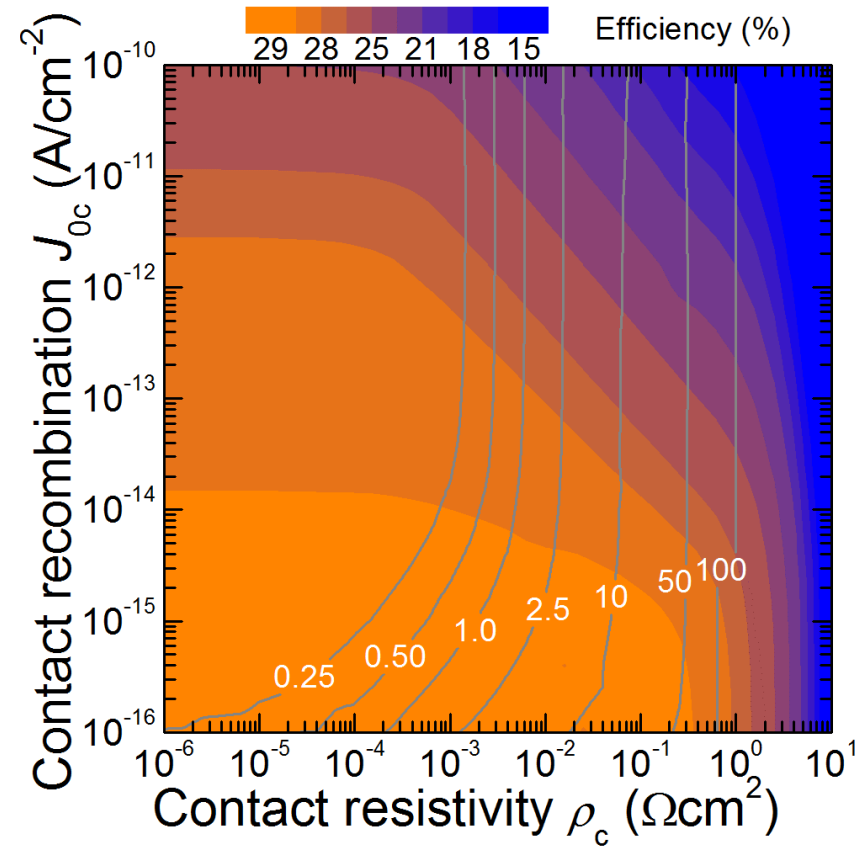
- Indicates the conductivity presented to the **collected** carrier

Contact recombination J_{oc}

- Indicates the conductivity presented to the **non-collected** carrier

Contact configuration

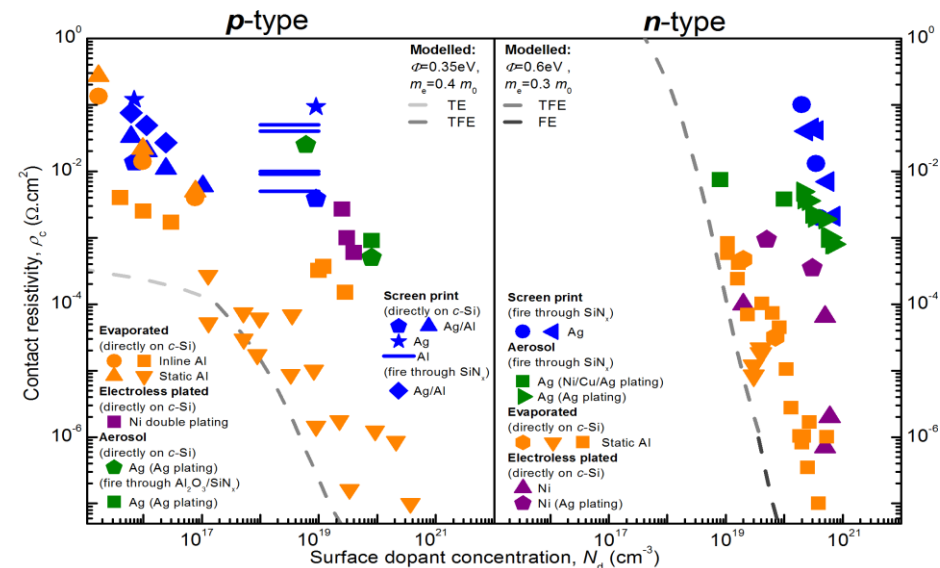
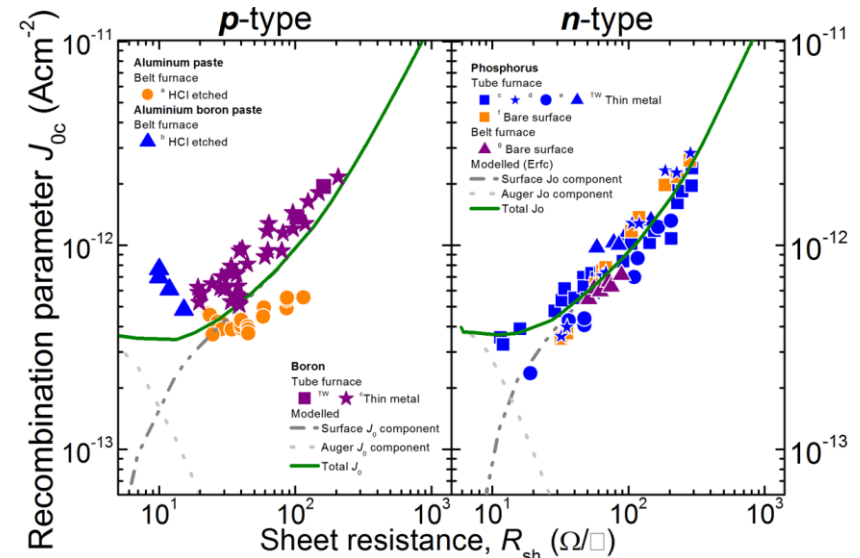
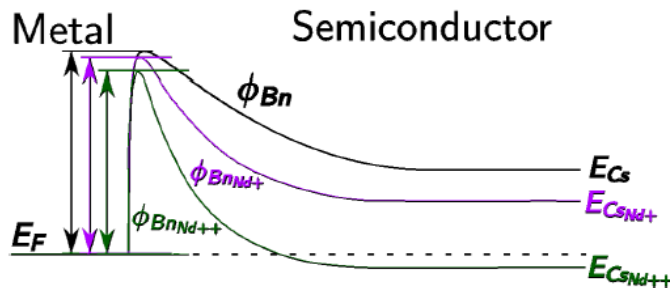
- Can further modulate the conductivities by adjusting the contact geometry



The priorities are all wrong



- Direct metal contacts exhibit poor selectivity
 - Large barrier heights (resistive)
 - High recombination
- Need to dope

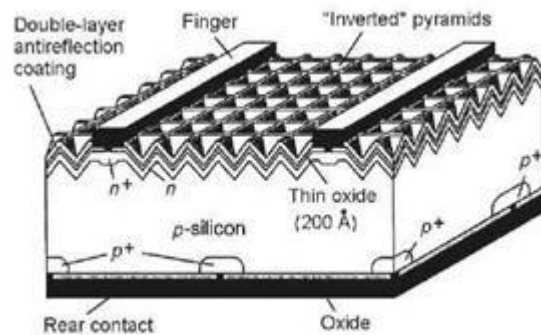


Solution: confine the contacts

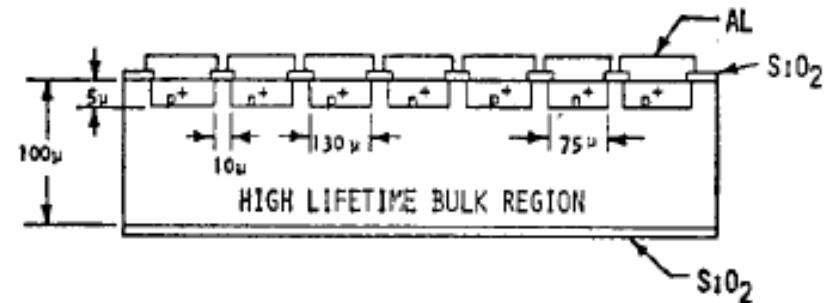


- Direct metal contacts exhibit poor selectivity
 - Large barrier heights (resistive)
 - High recombination
- Need to dope
- Efficiency potential demonstrated by 25% PERC/PERL cell (UNSW)

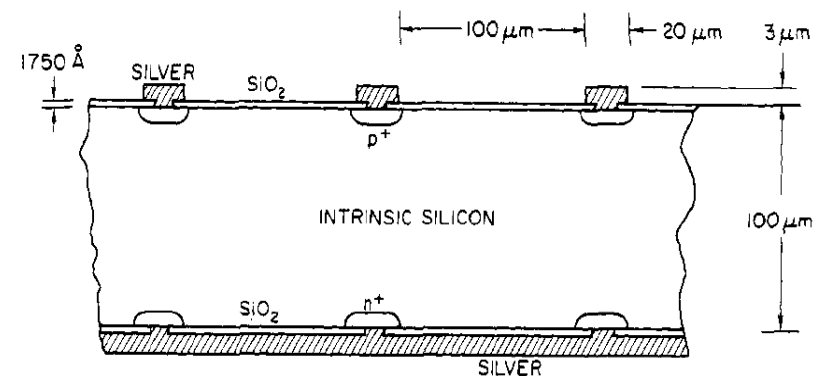
- Make the contacts as small as possible
- Passivate the other surfaces
- Maximise absorption



J. Zhao et al., *APL* (1998)



Schwartz and Lammert, *IEDM* (1975)



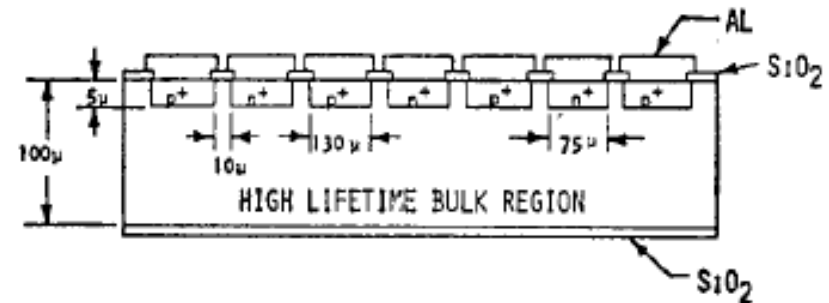
R. M. Swanson, *IEDM* (1978)

Solution: confine the contacts



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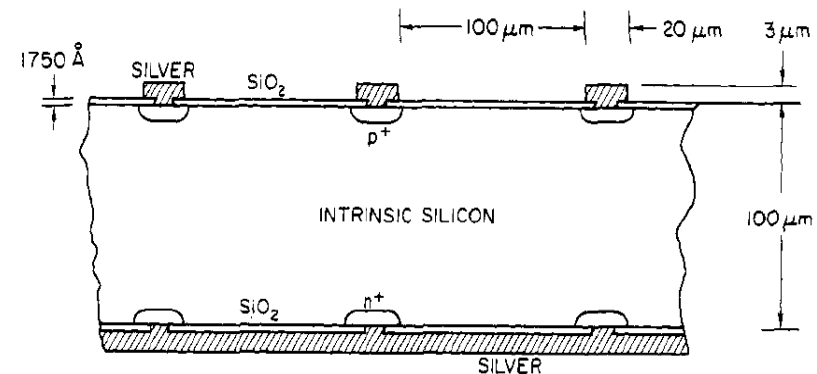
APPROACHING THE 29% LIMIT EFFICIENCY OF SILICON SOLAR CELLS

Richard M. Swanson
SunPower Corporation

NEEDED—NEW CONTACTS

None of the above discussed contacts permit cell efficiency over 25%. What is needed is a new contact that has J_0 less than 5 fA/cm^2 and makes good majority carrier contact. Two such contacts are needed, one for electrons and one for holes.

Schwartz and Lammert, *IEDM* (1975)

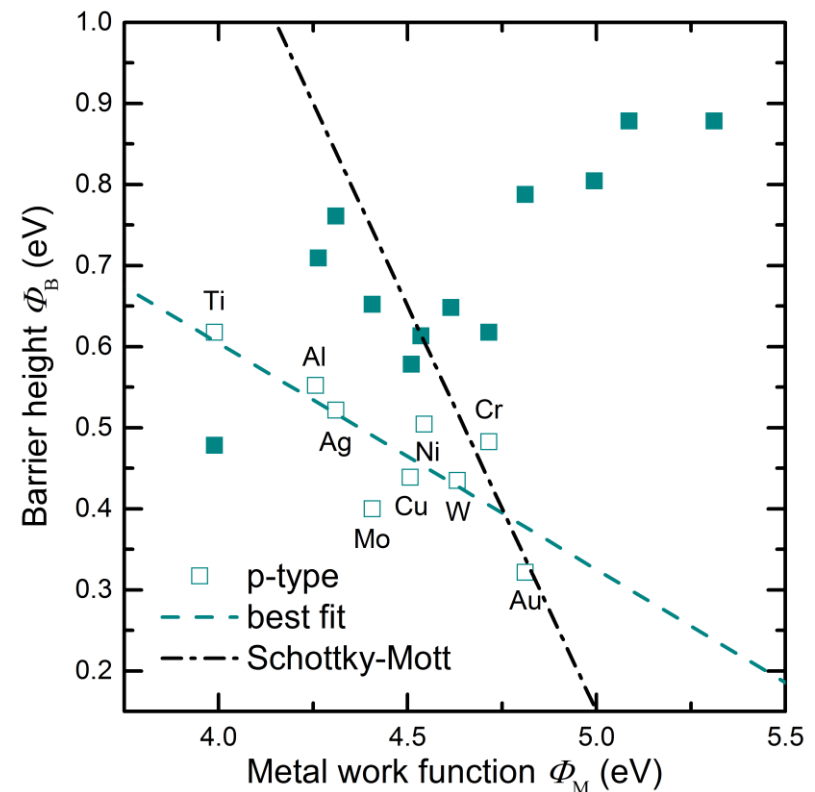
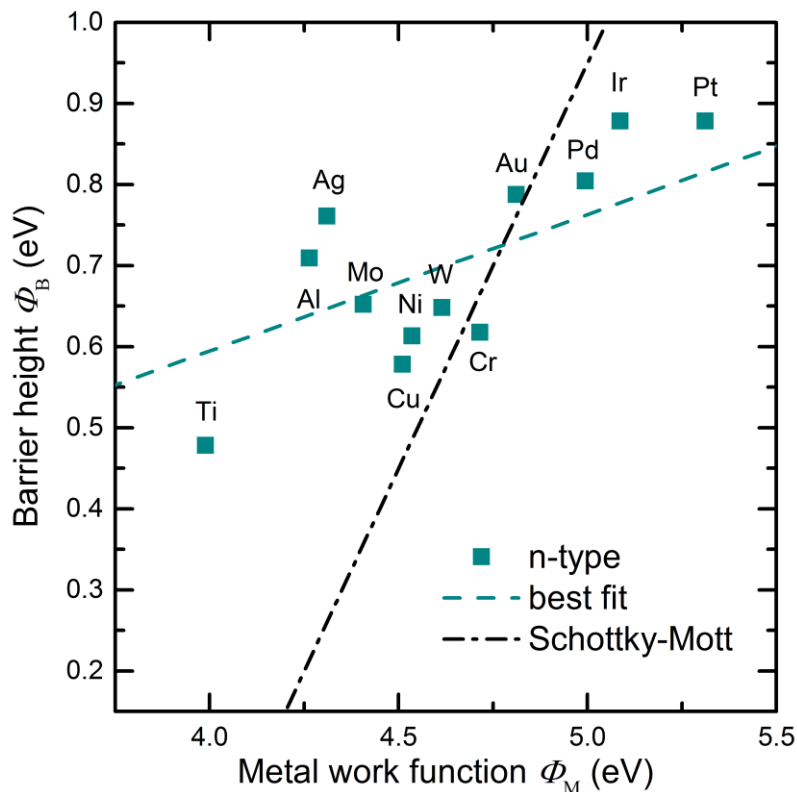


R. M. Swanson, *IEDM* (1978)

Fermi level pinning



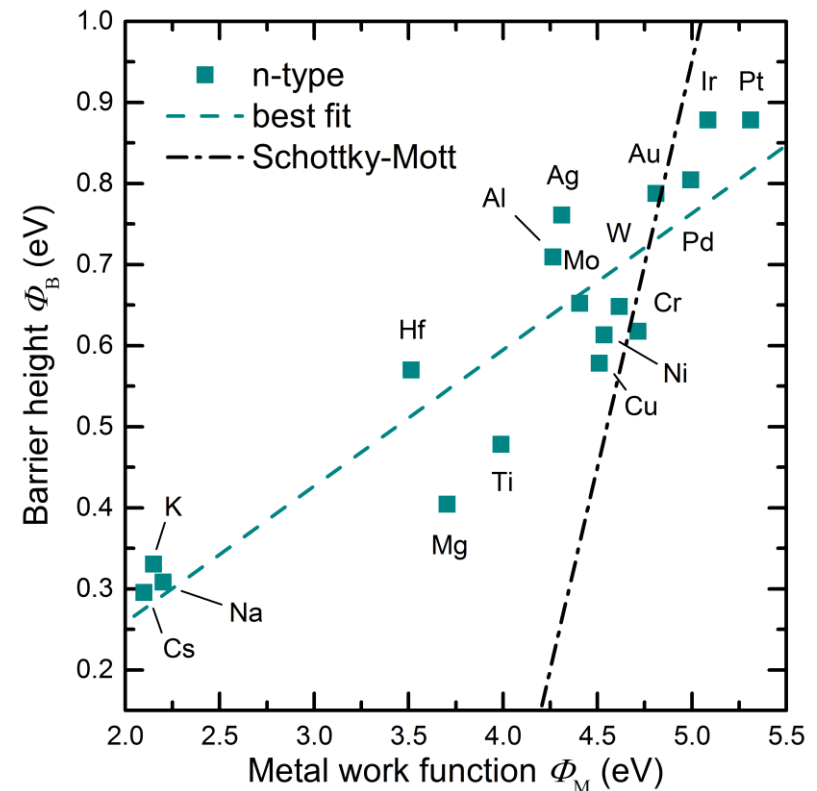
- **Harder to contact n-type silicon because of Fermi level pinning**
 - due to interface defects
 - typical barrier height > 0.7 eV for Al and Ag contacts
- **lower barriers tend to form at the p-type silicon / metal interface**
 - typical barrier height < 0.6 eV



'Extreme' work functions needed



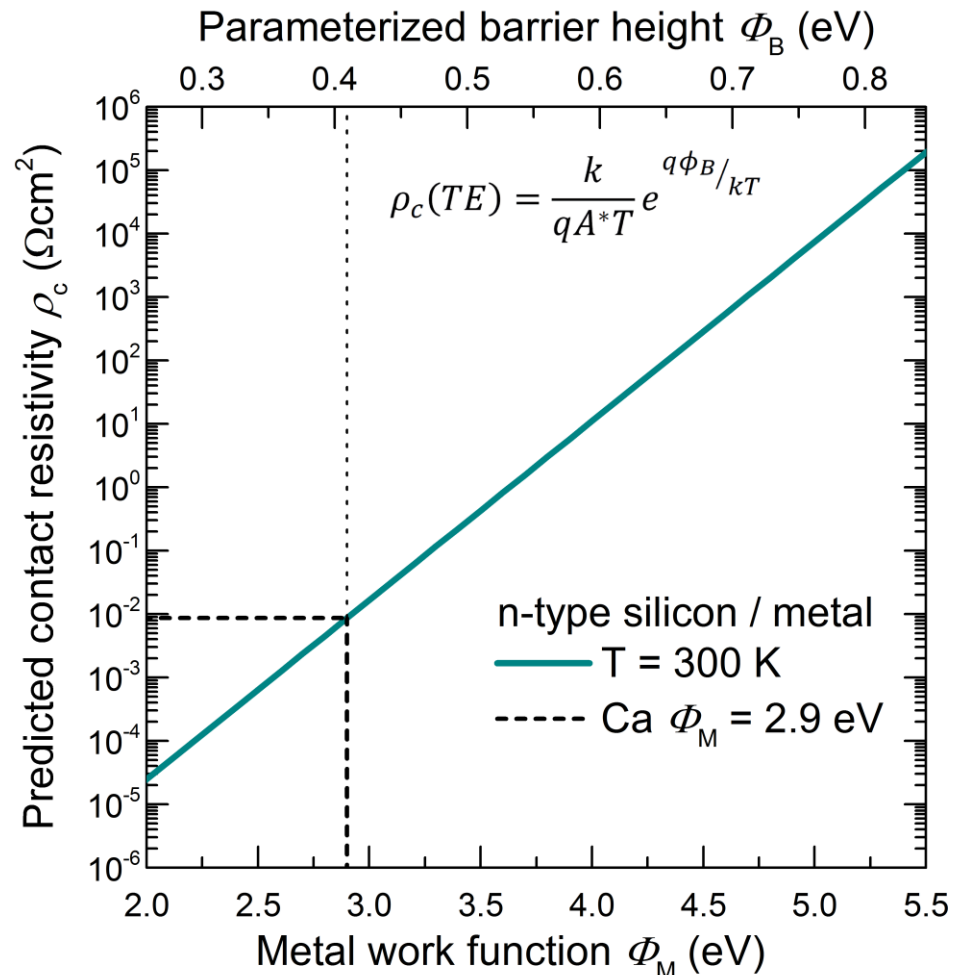
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 - typical barrier height < 0.6 eV
- **low barriers possible with low metal work function**



Proof-of-concept: Ca



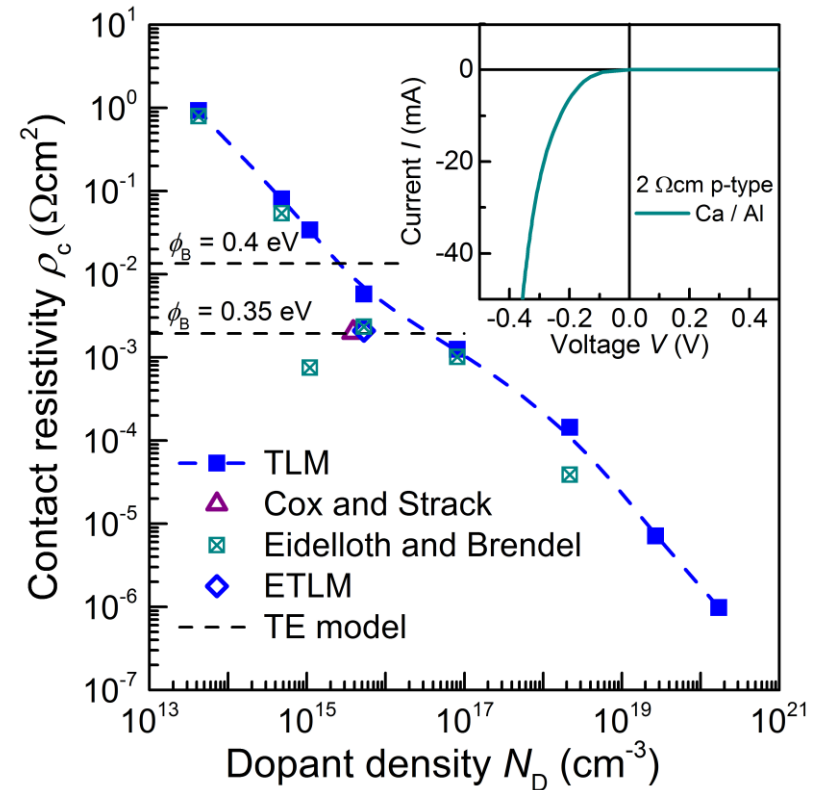
- **Using a linear parameterization we can predict barrier height formation vs metal work function**
 - input into thermionic emission model
 - can predict dopant-free contact resistivity
- **Calcium work function ~ 2.9 eV**
 - common electrode in OPV
 - predicted $\rho_c < 10 \text{ m}\Omega\text{cm}^2$
 - predicted $\phi_B \sim 0.4 \text{ eV}$



Calcium contacts



- Ohmic contact over all phosphorus dopant densities
- $\rho_c \sim 2\text{-}6 \text{ m}\Omega\text{cm}^2$ on (undiffused) $1 \text{ }\Omega\text{cm}$ n-type Si
 - similar to screen printed Ag on phosphorus diffused n^+
- rectifying contact to p-type
 - small barrier for electrons means large barrier for holes

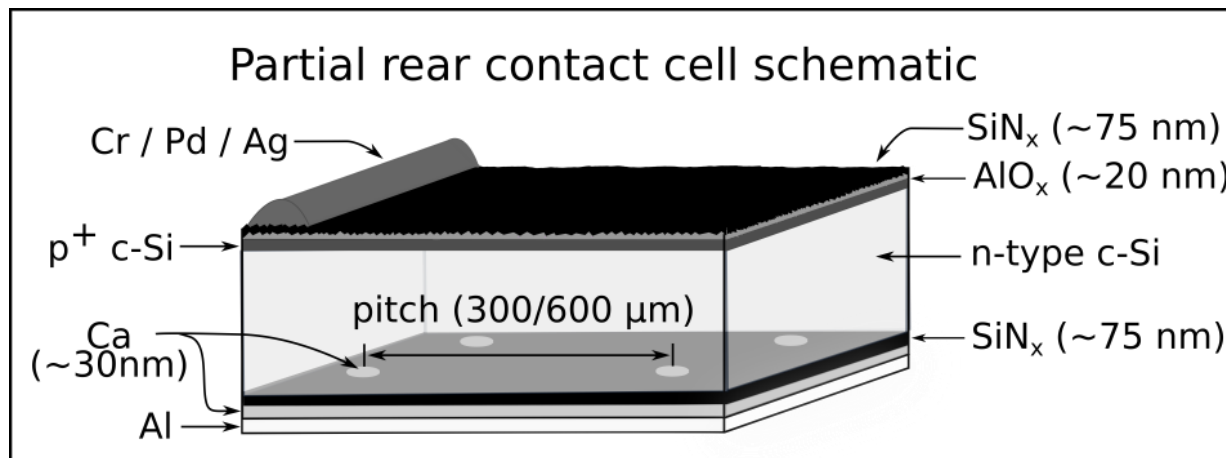


N-type PERC cells



- **4 PERC cells fabricated**
 - differing wafer resistivity 9.9 and 0.9 Ωcm
 - differing rear contact pitch (and so contact fraction) (1.26% and 0.32%)

	<i>contact fraction</i>	
<i>wafer ρ</i>	1.26%	0.32%
9.9 Ωcm	Cell 1	Cell 2
0.9 Ωcm	Cell 3	Cell 4

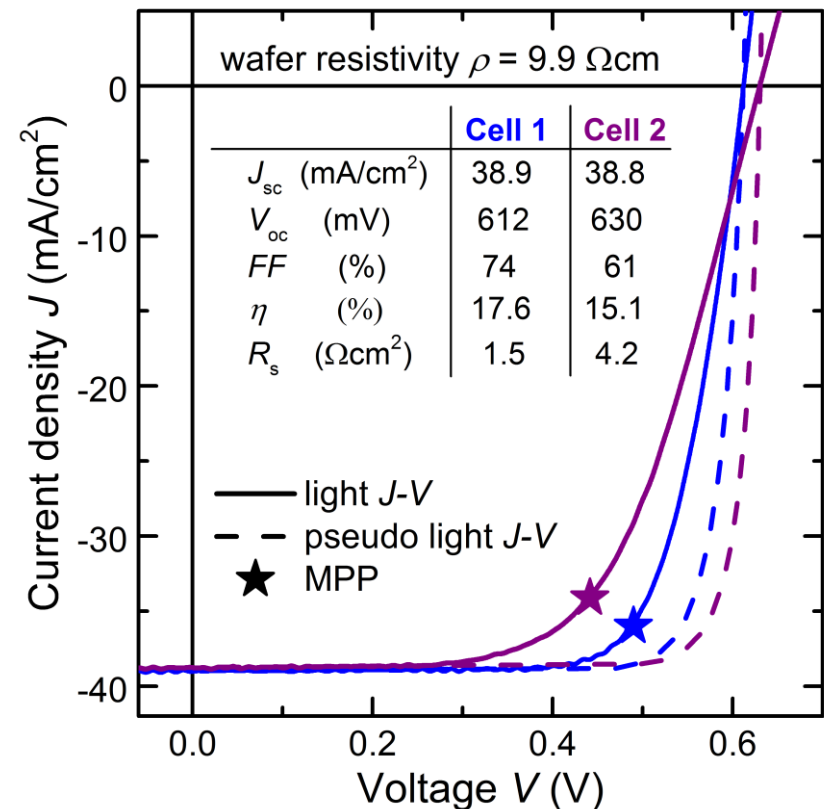


N-type PERC cells



- **low dopant density**
 - $N_D = 4.5 \times 10^{14} \text{ cm}^{-3}$
- **high R_s for both cells**
- **low V_{oc}**
 - due to recombination at the contacts
- **Cell 1 (larger contact fraction)**
 - $\eta = 17.6\%$

	contact fraction	
wafer ρ	1.26%	0.32%
9.9 Ωcm	Cell 1	Cell 2
0.9 Ωcm	Cell 3	Cell 4

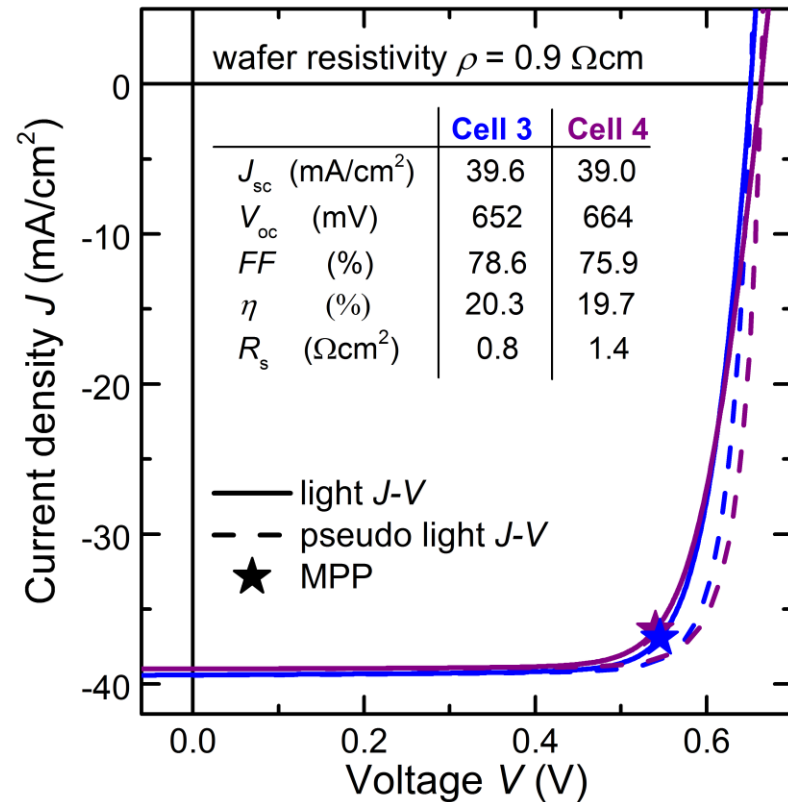


N-type PERC cells



- moderate dopant density
 - $N_D = 5.4 \times 10^{15} \text{ cm}^{-3}$
- improvement in all device performance metrics
 - much higher V_{oc}
 - much lower R_s
- Cell 3 (larger contact fraction)
 - $\eta = 20.3\%$

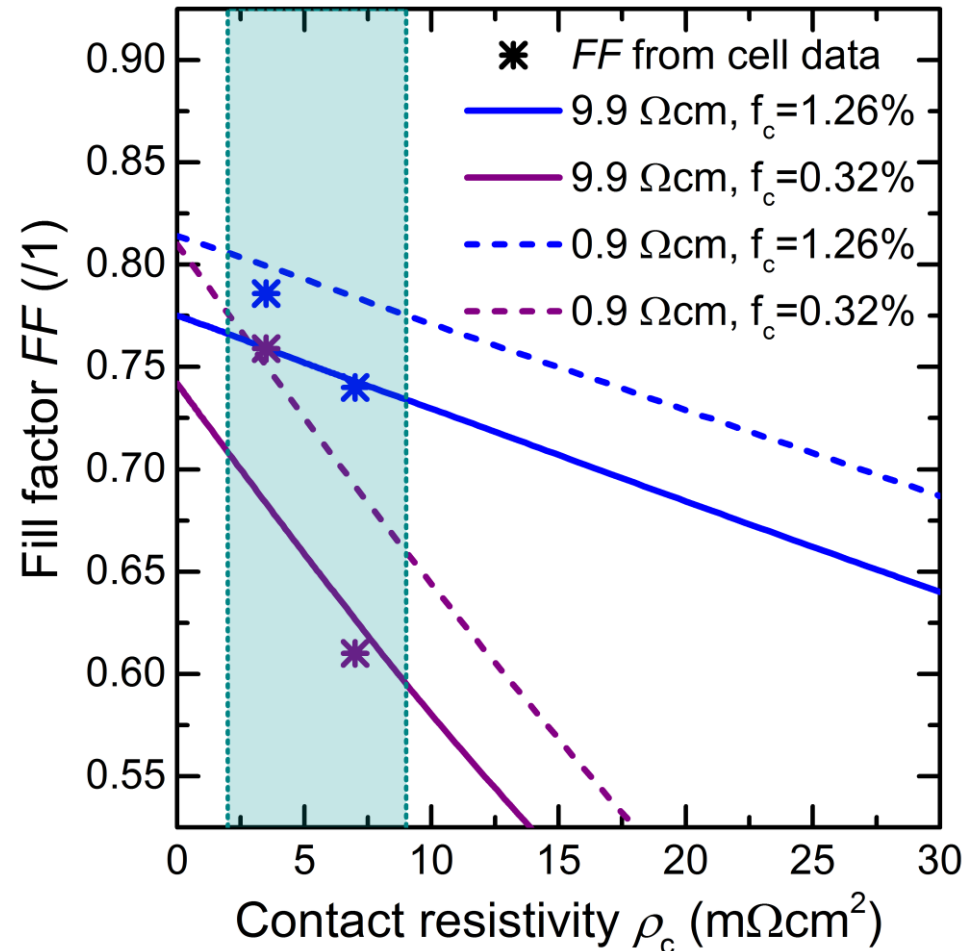
	contact fraction	
wafer ρ	1.26%	0.32%
9.9 Ωcm	Cell 1	Cell 2
0.9 Ωcm	Cell 3	Cell 4



Confirming ρ_c



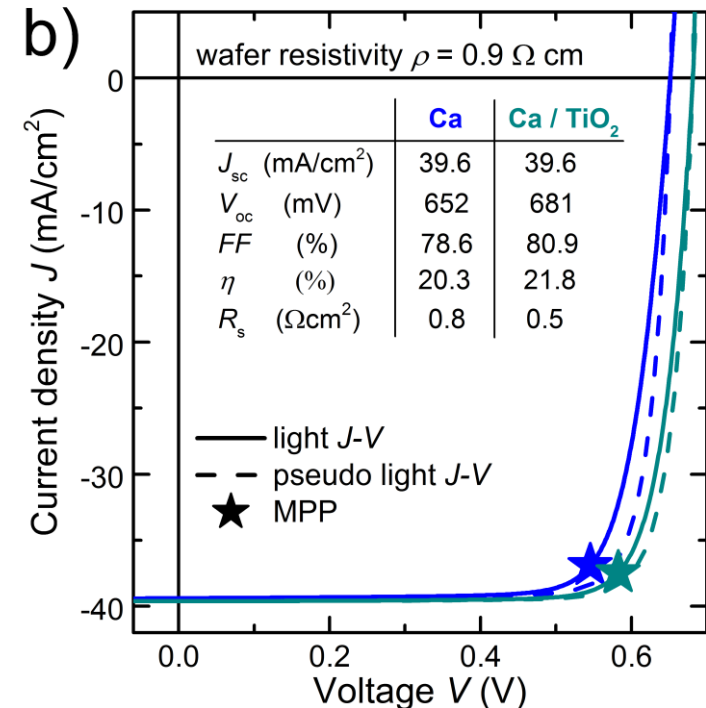
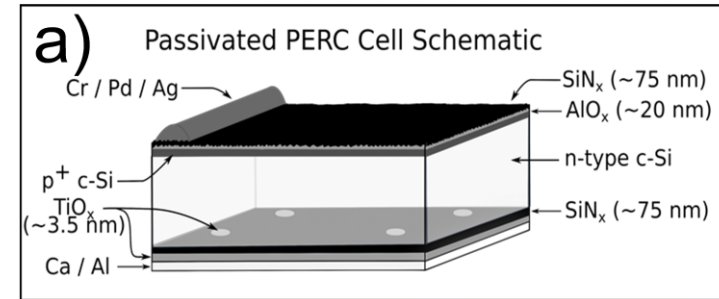
- **Modelling in QSCell_PRC**
- **low f_c cells sensitive to ρ_c**
- **rear contact $\rho_c \sim 5 \pm 3 \text{ m}\Omega\text{cm}^2$**
 - contact resistivity only slightly higher on 9.9 Ωcm wafer
 - consistent with thermionic emission model
 - previous ρ_c results due to bulk resistance effects



Passivated PERC cells



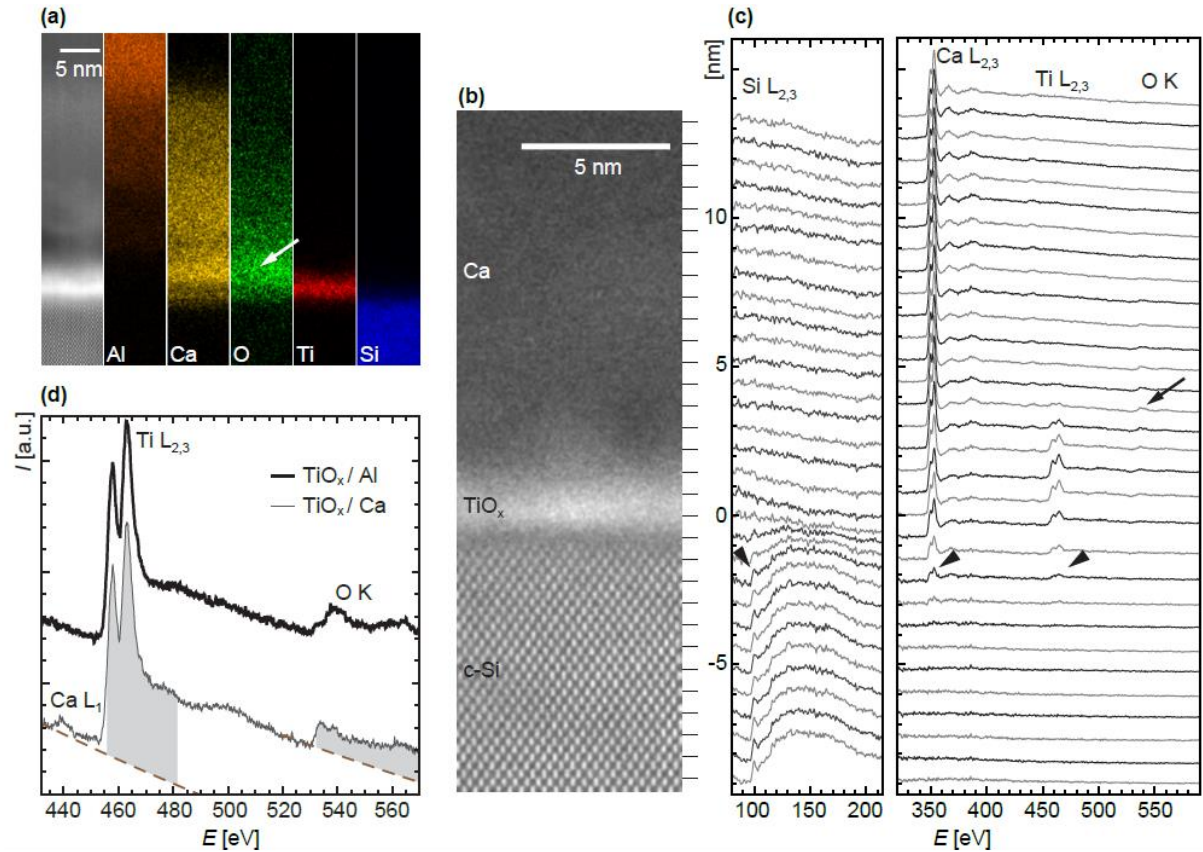
- **similar structure as Cell 3**
 - $\rho = 0.9 \Omega\text{cm}$
 - $f_c = 6\%$
- **insertion of a passivating TiO_2 interlayer ($\sim 3.5 \text{ nm}$)**
 - increase cell voltage
 - decrease series resistance
 - improvement in rear contact resistivity?
 - $\eta = 21.8\%$
- **Other interlayers were less successful:**
 - GaO_x and a-Si



A closer look at the contact



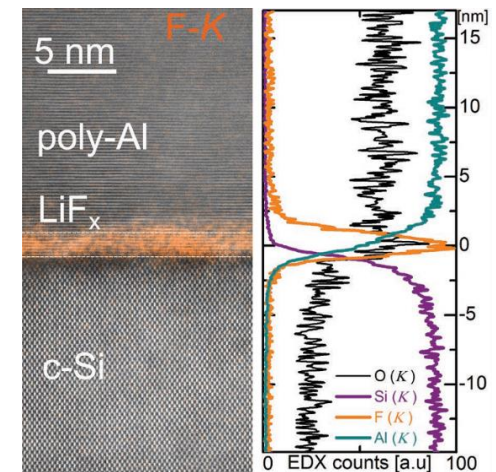
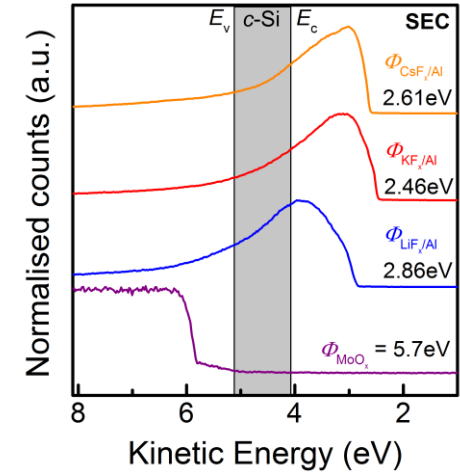
- **TiO₂ (as deposited)**
- **Oxygen accumulates at Ca / TiO_x interface**
 - Reducing TiO₂ to TiO
 - Also for Al / TiO_x contacts
- **Ca diffusion toward Si interface**
 - Low WF of Ca relative to Al lowers contact resistance



Another approach: LiF / Al



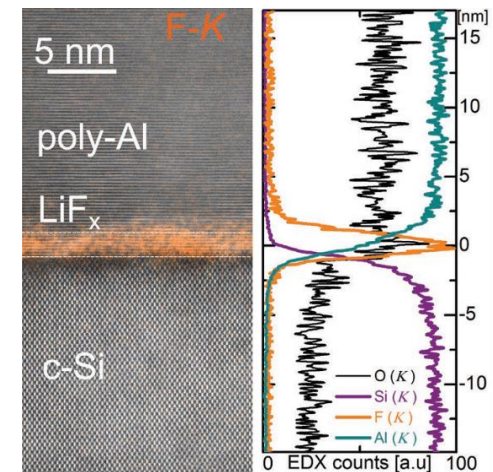
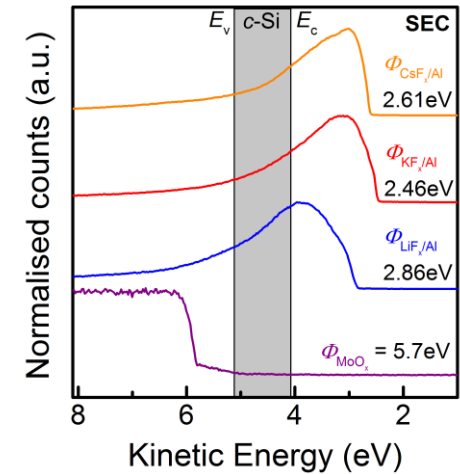
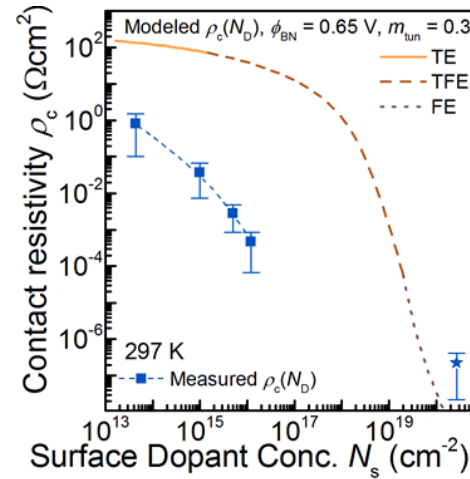
- Instead of using a low work function metal, lower the work function of Al
 - Thermally evaporated LiF / Al stack
 - $\phi \sim 2.9$ eV
 - transparent ($E_g > 6.8$ eV)



Another approach: LiF / Al



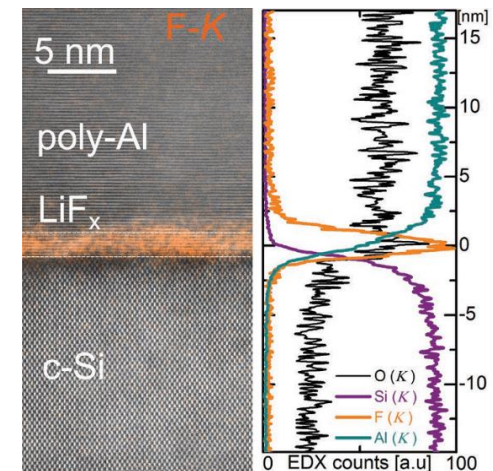
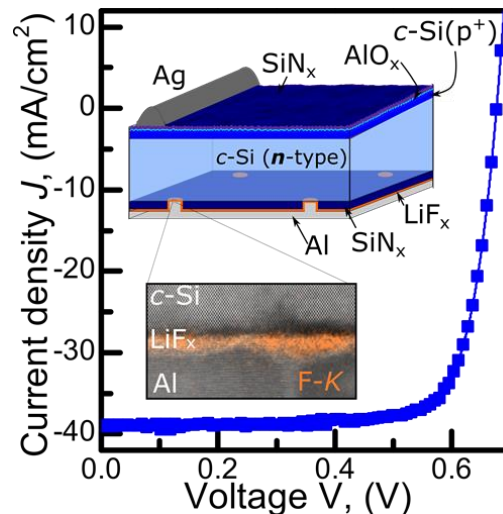
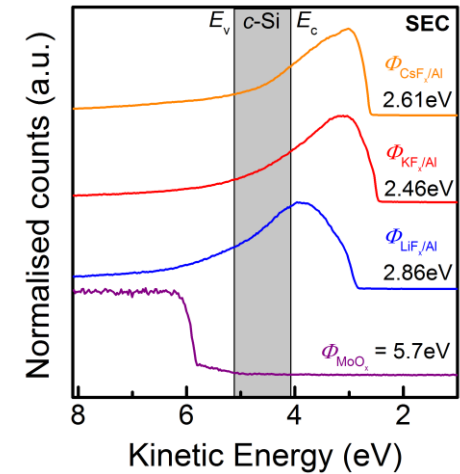
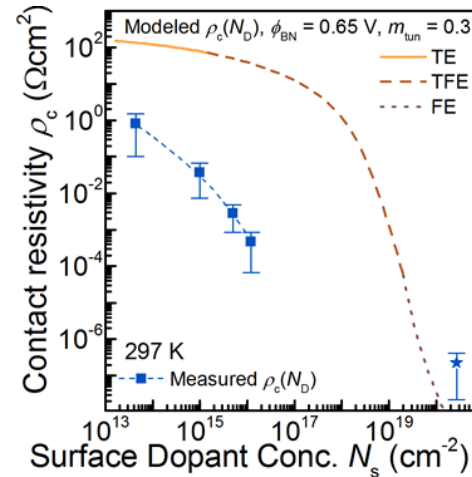
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 - transparent ($E_g > 6.8$ eV)
- $\rho_c \sim 1 \text{ m}\Omega\text{cm}^2$ (1 Ωcm n-type)



Another approach: LiF / Al



- Instead of using a low work function metal, lower the work function of Al
 - Thermally evaporated LiF / Al stack
 - $\phi \sim 2.9$ eV
 - transparent ($E_g > 6.8$ eV)
- $\rho_c \sim 1 \text{ m}\Omega\text{cm}^2$ (1 Ωcm n-type)
- LiF / Al PERC cell
 - $f_c \sim 1\%$
 - $\rho = 1 \Omega\text{cm}$
- Higher voltage than Ca PERC cells
 - $V_{oc} = 676$ mV
 - contact SRV $< 10^4$ cm/s
- $\eta = 20.6\%$



$$V_{oc} = 676 \text{ mV}, J_{sc} = 38.9 \text{ mA}/\text{cm}^2, FF = 78.9, \eta = 20.6\%$$

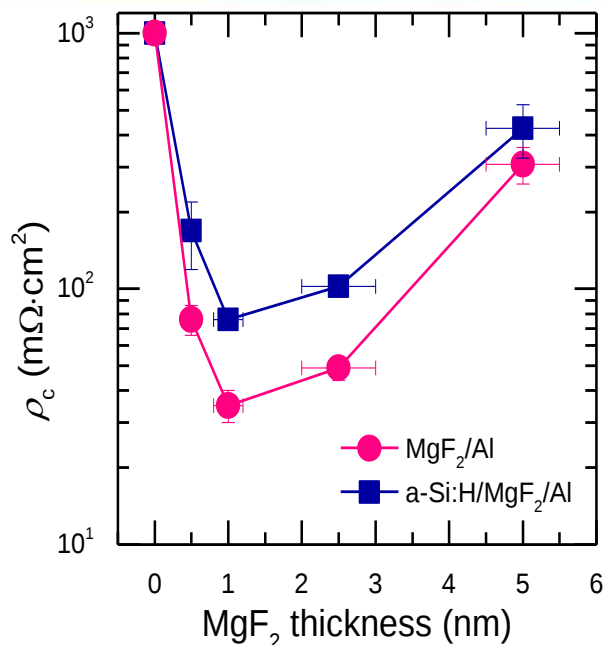
Bullock, J., et al, Adv. Energy Mater, 2016

Bullock, J., et al, Nature Energy, 1, 15031, 2016

Another approach: MgF_2 / Al



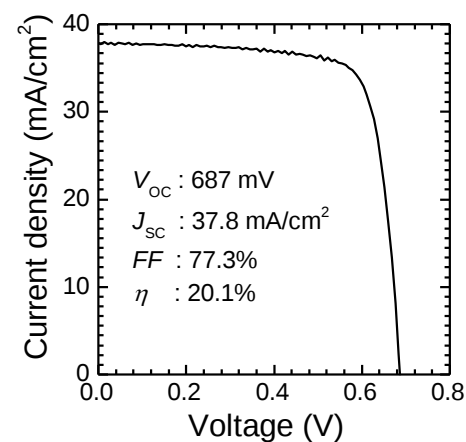
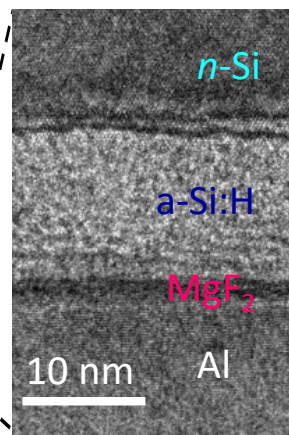
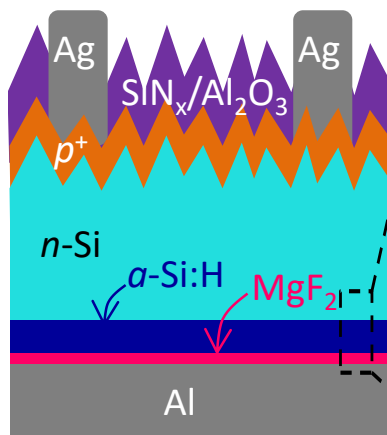
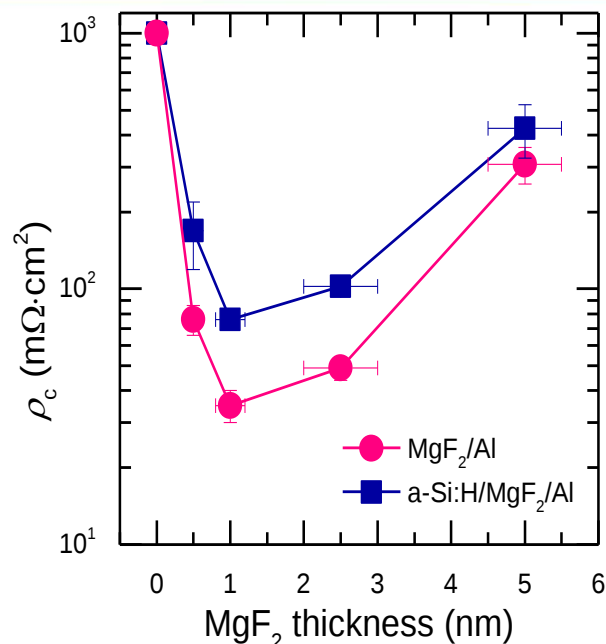
- Instead of using a low work function metal, lower the work function of Al
 - Thermally evaporated MgF_2 / Al stack
 - $\phi \sim 3.5$ eV
- direct Si $\rho_c \sim 35 \text{ m}\Omega\text{cm}^2$
- with a-Si $\rho_c \sim 80 \text{ m}\Omega\text{cm}^2$
 - $J_0 \sim 10 \text{ fA/cm}^2$



Another approach: MgF_2 / Al



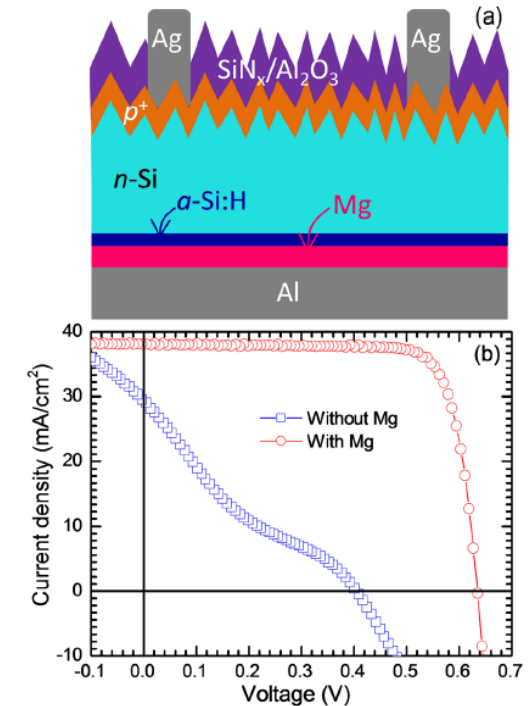
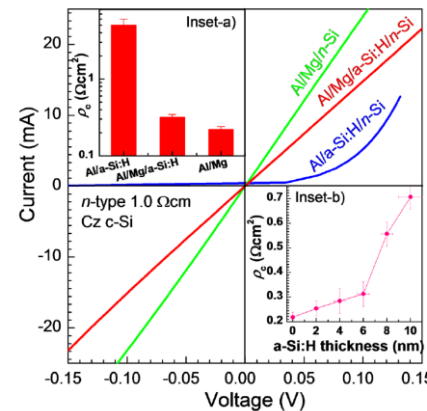
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- with a-Si $\rho_c \sim 80 \text{ m}\Omega\text{cm}^2$
 - $J_0 \sim 10 \text{ fA/cm}^2$
- Full rear area a-Si / MgF_2 / Al
- $V_{oc} = 687 \text{ mV}$
- $\eta = 20.1\%$



Also Mg...



- **Similar approach to Ca**
 - Potentially more stable and easier to evaporate
 - $\phi \sim 3.7$ eV
- **direct Si $\rho_c \sim 220$ m Ω cm²**
- **with a-Si (6 nm) $\rho_c \sim 310$ m Ω cm²**
- **Full rear area a-Si / Mg / Al**
- **$V_{oc} = 637$ mV**
 - Degradation of voltage due to interaction with a-Si layer?
- **$\eta = 19.0\%$**

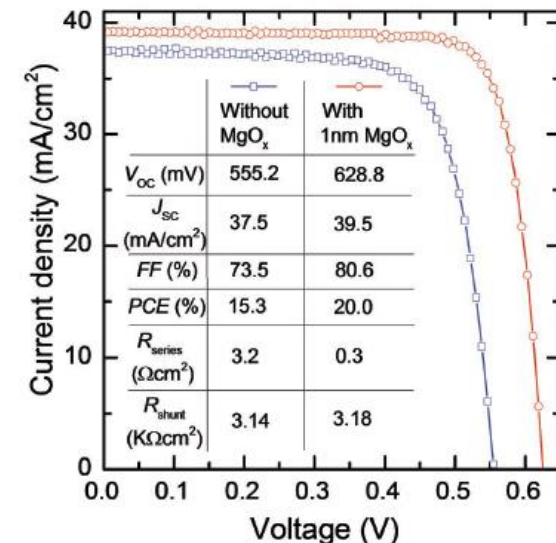
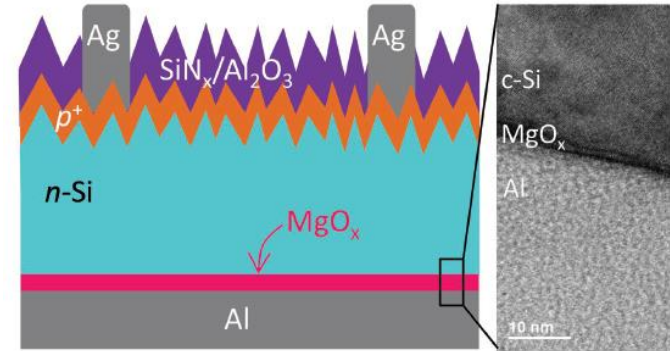


	V_{oc} (mV)	J_{sc} (mA/cm ²)	FF (%)	η (%)
Without Mg	405.0	29.5	18.2	2.2
With Mg	636.6	38.0	78.4	19.0

Also Mg, and MgO_x...



- **Similar approach to MoOx**
 - Thermal evaporation from powder source
 - O vacancy defect band
 - MgO_{0.75} (from XPS)
- **MgOx (1 nm) / Al $\rho_c \sim 18 \text{ m}\Omega\text{cm}^2$**
- **$\eta = 20.0\%$**
 - Stable up to 400 C
 - Poor passivation



Also Mg, and MgO_x, and others...



	Contact Characteristics			Deposition details
	I/V behavior	Extracted ρ_c (m Ω cm ²)	Extraction method	
Electron contacts c-Si(n)/TiO _x /Al c-Si(n)/TiO _x /LiF _x /Al c-Si(n)/TaO _x /Al c-Si(n)/ZnO _x /Al c-Si(n)/SnO _x /Al c-Si(n)/LiF _x /Al c-Si(n)/CsF _x /Al c-Si(n)/KF _x /Al c-Si(n)/C ₆₀ /Al c-Si(n)/CsO _x /Al	Ohmic Ohmic Non-linear Non-linear Non-linear Ohmic Ohmic Ohmic Ohmic Ohmic	30 490 N/A N/A N/A ~1 ~1 7.6 ~200 1.8	C&S C&S N/A N/A N/A C&S C&S C&S C&S C&S	TiO _x (Thermal ALD, 230°C, titanium tetraisopropoxide / water, 2.8nm) TiO _x (Thermal ALD, 230°C, titanium tetraisopropoxide / water, 6 nm). ALD, 250°C tantalum ethoxide / water, 10nm ALD, 200°C, diethylzinc / water, 10nm TE, powder source, ~1Å/sec, ~10 ⁻⁵ mbar, 15 nm TE, powder source, ~1Å/sec, ~10 ⁻⁶ mbar, ~1.5 nm TE, powder source, ~1Å/sec, ~10 ⁻⁶ mbar, ~1.5 nm TE, powder source, ~1Å/sec, ~10 ⁻⁶ mbar, ~1.5 nm TE, powder source, ~1Å/sec, ~10 ⁻⁵ mbar, ~5 nm TE, CsCO ₃ powder source, ~1Å/sec, ~10 ⁻⁵ mbar, 2 nm
Hole contacts c-Si(p)/MoO _x /Pd/Ag c-Si(p)/PEDOT:PSS/Pd/Ag c-Si(p)/CuPc/Au/Ag c-Si(p)/CuSCN/Al c-Si(p)/CuO _x :N/Pd/Ag	Ohmic Ohmic Ohmic Ohmic Ohmic	~1 50 ~300 58 11	C&S C&S TLM TLM C&S	TE, powder source, ~1Å/sec, ~10 ⁻⁶ mbar, ~10nm LPD, spin coated, Heraeus 4083, ~50nm TE, powder source, ~1Å/sec, ~10 ⁻⁵ mbar, 25 nm LPD, spin coated, 10mg/mL CuSCN in dipropyl sulphate Reactive sputtered, ~8nm

- Keep an eye out for an upcoming review paper for updated cell results...

What's next?

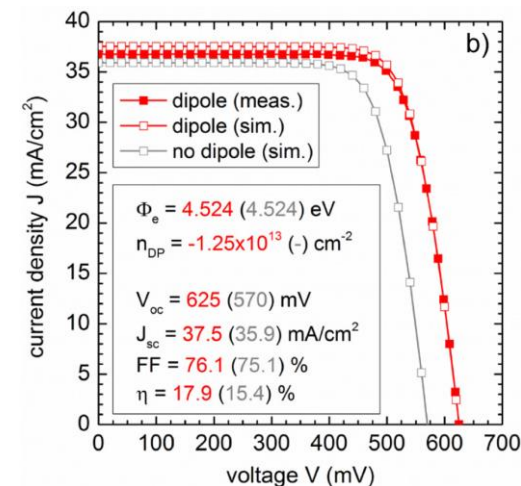
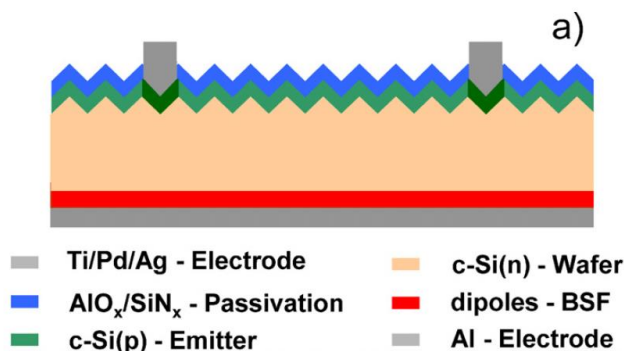
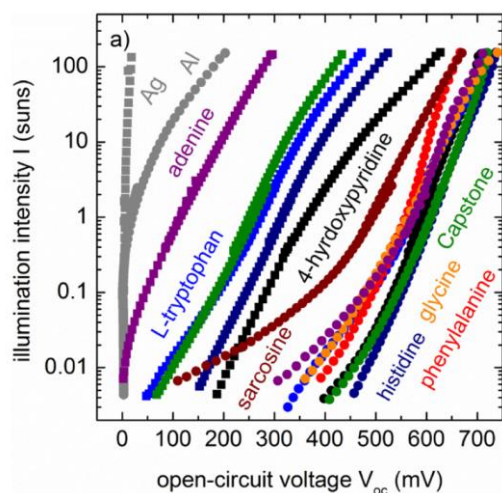


How Molecules with Dipole Moments Enhance the Selectivity of Electrodes in Organic Solar Cells – A Combined Experimental and Theoretical Approach

Uli Würfel,* Martin Seßler, Moritz Unmüssig, Nils Hofmann, Mathias List, Eric Mankel, Thomas Mayer, Günter Reiter, Jean-Luc Bubendorff, Laurent Simon, and Markus Kohlstädt

Electron-selective contacts via ultra-thin organic interface dipoles for silicon organic heterojunction solar cells

Christian Reichel, Uli Würfel, Kristina Winkler, Hans-Frieder Schleiermacher, Markus Kohlstädt, Moritz Unmüssig, Christoph A. Messmer, Martin Hermle, and Stefan W. Glunz



Conclusion

- **Many materials out there!**
 - We learnt a lot over a very short time period
 - Read widely! (Think creatively but critically)
- **Passivation is critical (and hard)**
 - Success likely to come from leveraging off materials like a-Si and SiO_x
- **Stability is largely overlooked**
 - Any material must be stable for 20+ years





Join the team:

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